

AMENDMENTS TO CLAIMS

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1-13. (Canceled)

14. (Currently Amended) A method for manufacturing a flexible panel comprising:

(a) providing a first substrate having a plurality of functional switches or conducting lines thereon;

(b) bonding a second substrate on said plurality of functional switches or conducting lines;

(c) thinning said first substrate to a predetermined thickness;

(d) adhering or sealing ~~a fifth a removable~~ substrate on said first substrate;

(e) removing said second substrate;

(f) forming a plurality of light valves, light-emitters, or conducting layers on said plurality of functional switches or conducting lines;

(g) removing said ~~fifth removable~~ substrate ~~on~~ ~~from~~ said first substrate; and

(h) coating a flexible polymer on the surface of said plurality of light valves, light-emitters, or conducting layers and said first substrate.

15. (Original) The method as claimed in claim 14, wherein said first substrate is a glass substrate.

16. (Original) The method as claimed in claim 14, wherein said thinning method in step (c) is polishing, cutting, or etching.

17. (Original) The method as claimed in claim 14, wherein said switch is a thin film transistor.

18. (Original) The method as claimed in claim 14, wherein said first substrate is thinned to have a thickness ranging from 30 to 100 μm .

19. (Original) The method as claimed in claim 14, wherein the coating method in step (h) is immersion or spin coating.

20. (Original) The method as claimed in claim 14, wherein the thickness of said polymer ranges from 1 to 10 μm .